



PRESS RELEASE

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TechSearch International Makes Sense of Package Alphabet Soup

With new packages continuously being introduced, TechSearch International's latest Advanced Packaging Update focuses on making some sense out of the alphabet soup of package options for split die. Application targets range from high-performance solutions for devices such as FPGAs to application processors found in mobile devices. SLIM, SWIFT, EMIB, NTI, and SLIT are high-density substrates without through silicon vias (TSVs). Fan-out wafer level packages (FO-WLPs) also provide an option for a split die package. Roadmaps from FO-WLP suppliers show the transition to finer features.

Package options for power devices are also discussed, including a special section on automotive packages. A detailed analysis focuses on the trends in Cu clip packages for MOSFETs. A double-digit growth rate is projected for this increasingly popular package. Also included is an update on the market for embedded component packages with a new market forecast split into actives and passives.

The detailed analysis is based on the company's 27-year history of studying markets and critical technology and infrastructure issues in advanced packaging. The 37-page report with full references provides analysis on these important developments. A set of 30 PowerPoint slides accompanies the report.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 17,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see <http://www.techsearchinc.com>.